Am29PL142

Am29PL142

Field-Programmable Controller (FPC)

DISTINCTIVE CHARACTERISTICS

- Implements complex state machines
- 8 conditional inputs, 16 outputs 128-word by 34-bit PROM
- Up to 20-MHz clock rate, 28-pin DIP
- 28 instructions
 - Conditional branching
- Conditional looping
- Conditional subroutine call
- Multiway branch

- · Output instruction presents counter contents at the control outputs for implementing a larger class of statemachine designs
- A controller-expansion (EXP) fuse provides address to
- external registered PROMs for more than 16 outputs SSR fuse configures Serial Shadow Register (SSRTM) diagnostics on chip

GENERAL DESCRIPTION

The Am29PL142 is a single-chip Field-Programmable Controller (FPC) that allows implementation of complex state machines and controllers by programming the appropriate sequence of instructions. Jumps, loops, and subroutine calls, conditionally executed based on the test inputs, provide the designer with powerful control flow primitives.

Intelligent control may be distributed throughout the system by using FPCs to control various self-contained functional units, such as register file/ALU, I/O, interrupt, diagnostic, and bus-control units.

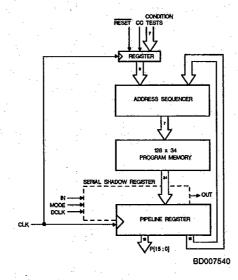
An address sequencer, the heart of the FPC, provides the address to an internal 128-word by 34-bit PROM. The fuse programming algorithm is almost identical to that used for AMD's Programmable Array Logic family.

The Am29PL142 can be expanded to address external registered PROMs by using the EXP fuse option to output the program-memory address through the control output pins P[14:8].

A counter register is provided and an instruction is available to present the counter-register contents at the control outputs P[14:8]. Using this, the control outputs can be dynamically modified for implementing a larger class of state machines.

As an option, the Am29PL142 may be programmed to have on-chip SSR diagnostics capability. Instructions can be serially shifted in, executed, and the results shifted out to facilitate system diagnostics.

SIMPLIFIED BLOCK DIAGRAM

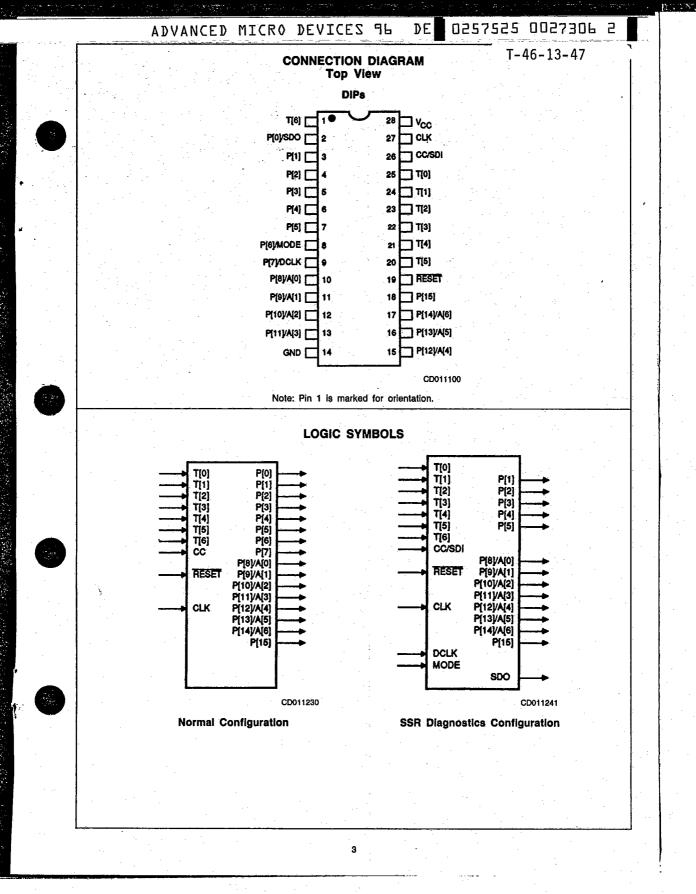


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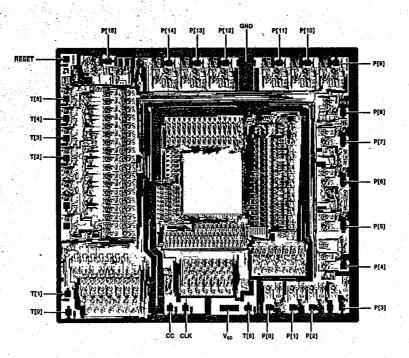
T-46-13-47 RELATED AMD PRODUCTS

Part No.	Description
Am29C01-1	High-Speed CMOS 4-Bit Microprocessor Slice
Am29C10A-1	High-Speed CMOS 12-Bit Sequencer
Am29C101-1	High-Speed CMOS 16-Bit Microprocessor
Am29114	8-Level Real-Time Interrupt Controller (Expandable)
Am29116	16-Bit Bipolar Microprocessor (Supports 100 ns System Cycle Time)
Am29C116	CMOS Version of Am29116
Am29C116-1/-2	High-Performance Versions of Am29C116
Am29117	2-Port Version of Am29116
Am29C117	CMOS Version of Am29117
Am29C117-1/-2	High-Performance Versions of Am29C117
Am29118	8-Bit Am29116 I/O Support
Am29130	16-Bit Barrel Shifter (Expandable)
Am29PL131	24-Pin Slim DIP Version of the Am29PL141
Am29LPL131	Low Power Version of Am29PL131
Am2914	Vectored Priority Interrupt Controller
Am29LPL141	Low-Power Version of the Am29PL141
Am29PL141	Field-Programmable Controller
Am29CPL141	CMOS Version of the Am29PL141
Am29CPL144	CMOS High-Density Field-Programmable Controller
Am29C325	CMOS 32-Bit Floating Point Processor
Am29C327	CMOS Double-Precision Floating Point Processor
Am29337	16-Bit Bounds Checker
Am2940	DMA Address Generator
Am29C516A-1	35-ns CMOS 16 x 16 Multiplier
Am29818	SSR Diagnostics Pipeline Register
Am29C818	CMOS Version of the Am29818



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METALLIZATION AND PAD LAYOUT



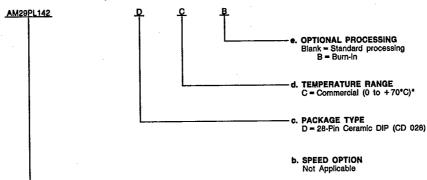
Die Size: 0.261" x 0.238"

Gate Count: 600 Equivalent Gates and 4K of PROM

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: a. Device Number
b. Speed Option (if applicable)

c. Package Type d. Temperature Range

e. Optional Processing



. DEVICE NUMBER/DESCRIPTION Am29PL142 Field Programmable Controller (FPC)

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

*The Commercial Operating Range is 0 to +85°C Case temperature for the Leadless Chip Carrier Package, due to the power constraints of that particular package.

MILITARY ORDERING INFORMATION **APL Products**

T-46-13-47

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. The order number (Valid Combination) is formed by a combination of:

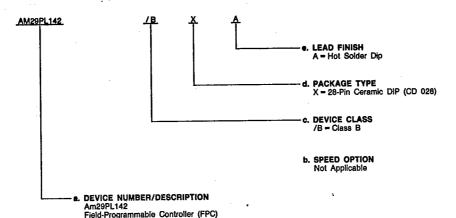
a. Device Number

b. Speed Option (if applicable)

c. Device Class

d. Package Type

e. Lead Finish



1	Valid Com	nbinations
	AM29PL142	/BXA

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check for newly released valid combinations.

Group A Tests

Group A tests consists of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

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PIN DESCRIPTION

CC[SDI] Condition Code — TEST (Input)

Internally synchronized condition code test input is selected through the 4-bit test-condition select field. In the SSR mode, CC is also the Serial Data Input (SDI).

Clock (Input)

The rising edge of the clock latches the PC register, count register, stack register, instruction-pipeline register, testinput register, CC register, reset register, and the EQ flag.

Upper General-Purpose Control P[15], P[14:8]/A[6:0] (Outputs)

The upper eight general-purpose control outputs are enabled by the OE bit from the instruction-pipeline register. When OE is HIGH, these outputs are enabled; when OE is LOW, they are three stated.

A controller Expansion (EXP) fuse can be programmed to set pins P[14:8] to output the program address A[6:0] from the PC MUX. These can be used to address external registered PROMs to provide more control outputs.

The contents of the internal count register (CREG) can also be routed to the control output pins P[14:8], using the OUTPUT instruction. Thus, the control outputs can be changed dynamically.

Lower General-Purpose Control (Outputs)

The lower eight general-purpose control outputs are permanently enabled. In the SSR diagnostics mode, P[7] becomes the diagnostic clock input (DCLK), P[6] becomes the diagnostic control input (MODE), and P[0] becomes the Serial Data Output (SDO). Both SDO and SDI are clocked by DCLK under control of the MODE bit.

RESET Internally Synchronized Reset (Input)

After it goes LOW, RESET is latched internally on the first rising edge of the clock. During the first clock cycle, the PC MUX is set to all ones (address 127). On the next rising edge of the clock, the program-memory contents at location 127 are loaded into the pipeline register. The EQ flag is also cleared at this time.

T[6:0] Internally Synchronized Test (Inputs)

In conditional instructions, these inputs are selected according to the 4-bit test condition select field. The inputs T[6:0] can also be used either as a branch address or as a value to be loaded into CREG depending on the instruction.

Program Memory

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Figure 1, the detailed block diagram of the Am29PL142 FPC, shows logic blocks and interconnecting buses that permit parallel performance of different operations in a single instruction. The FPC consists of four main logic blocks: the program memory, address control logic, condition code selection logic, and instruction decode. A fifth optional block is the Serial Shadow Register (SSR).

The program memory contains the user-defined instruction flow and output sequence. The address control logic addresses the program memory. This control logic supports highlevel instruction functions including conditional branches, subroutine calls and returns, loops, and multiway branches. The condition code selection logic selects the condition code input to be tested when a conditional instruction is executed. The polarity of the selected condition code input is controlled by the POL bit in the microword. The instruction decode generates the control signals necessary to perform the instruction specified by the instruction part (P[33:16]) of the microword. The SSR enables in-system testing to isolate problems down to the IC level.

The FPC program memory is a 128-word by 34-bit PROM with a 34-bit pipeline register at its output. The upper 18 bits (P[33:16]) of the pipeline register are internal to the FPC and form the instruction to control address sequencing. The format for instructions is: a 1-bit synchronous Output Enable OE, a 5-bit OPCODE, a 1-bit test polarity select POL, a 4-bit TEST condition select field, and a 7-bit immediate DATA field. The DATA field is used to provide branch addresses, test input masks, and counter values.

The lower 16 bits (P[15:0]) of the pipeline register are brought out as user-defined, general purpose control outputs. The upper eight control outputs (P[15:8]) are three-stated when OE is programmed as a LOW. The lower eight control bits (P[7:0]) are always enabled.

Outputs P[14:8] will contain the next instruction address when the optional EXP fuse is programmed. The contents of the CREG can be sent to outputs P[14:8], regardless of whether the EXP fuse is programmed.

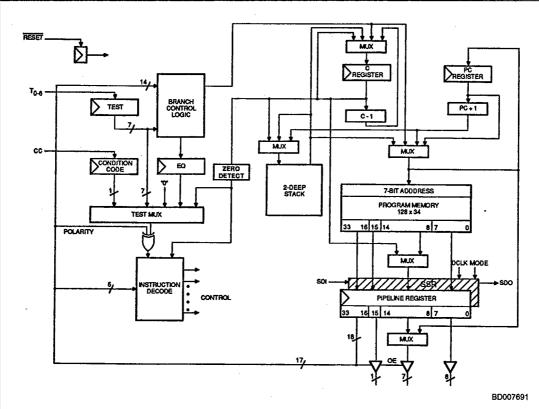


Figure 1. Am29PL142 Detailed Block Diagram

Address Control Logic

The address control logic consists of four logic blocks:

PC GRP - the program counter multiplexer (PC MUX), program counter register (PC) and combinatorial incrementer (PC + 1)

STACK – subroutine multiplexer (S MUX) with a 2-word by 7-bit-wide stack

CNTR - count register (CREG) with counter multiplexer (C MUX), combinatorial decrementer (CREG - 1), and zero detect on count register

GOTO - multifunction branch control logic

PC GRP

The PC GRP consists of a 4:1 multiplexer, a program counter (PC) register, and a 7-bit combinatorial incrementer (PC + 1). It selects the PC, PC + 1, the branch address, or the top of stack as the next instruction address input to the program memory and the PC.

RESET is latched internally on the first rising edge of the clock after it goes LOW. During the first clock cycle, the PC MUX is set to all ones (address 127). On the next rising edge of the clock, the program memory contents at location 127 are loaded into the pipeline register.

STACK

The stack block consists of a 3:1 multiplexer (S MUX) that stores the data into the topmost location of the stack. The S MUX chooses from three sources: PC + 1, count register, and the top of the stack (for holding). PC + 1 is the input source when doing subroutine calls. PC MUX is the output destination when a return-from-subroutine instruction is performed.

CNTR

The CNTR block consists of a 4:1 multiplexer (C MUX) feeding a 7-bit count register (CREG) which, in turn, outputs to a combinatorial decrementer (CREG – 1) and a zero-detect circuit. The CNTR block is typically used for timing functions and iterative loop counting.

The C MUX has the following input sources: top of stack, the branch-logic output, CREG - 1, and the CREG (for holding).

GOTO

The GOTO (branch control) logic block performs three functions:

It provides a 7-bit value directly from the DATA field in the instruction pipeline register.

It provides a 7-bit branch address from the TEST inputs T[6:0] masked by the DATA field from the instruction pipeline register.

It compares the TEST inputs T[6:0] (masked by the DATA field in the instruction pipeline register) with the constant field comparison (see Instruction Format) in the pipeline register.

The EQ flip-flop is set according to the following expression:

EQ = [(TEST .AND. DATA) .XNOR. constant] .OR. EQ

The EQ flag can be tested by the condition-code selection logic. Multiple tests of any group of T inputs in a manner analogous to sum-of-products can be performed, since a no-

match comparison does not reset the EQ flag. Any conditional branch on EQ will reset the EQ flag. Conditional returns on EQ will not change the EQ flag. RESET input LOW will reset the EQ flag.

NOTE: A zero in the DATA field blocks the corresponding bit in the TEST field; a one activates the corresponding bit.

The constant field bits that correspond to masked test field bits must be zero. A zero is substituted for masked test field bits. This masking operation is independent of the value of the POL bit.

Condition Code Selection Logic

The condition code selection logic consists of a 16:1 multiplexer. The 16 condition inputs are the seven test bits, the condition code input CC, the EQ flag, CREG ZERO status, and six UNCOND test conditions connected to zero for the unconditional mode. The TEST field in the pipelline register (P[26:23]) selects one of the 16 conditions. If one of the UNCOND is chosen, and the POL bit is a one, the instruction is executed with a "forced PASS" condition. If one of the UNCOND is chosen, and the POL bit is a zero, the instruction is executed with a "forced FAIL" condition. See opcode descriptions for more details.

The polarity bit POL in P[27] of the instruction pipeline register allows the user to test for either pass/true or fail/false condition. Refer to Table 2 for details.

Instruction Decode

The instruction decoder is a PLA that generates the control for 28 different instructions. The decoder inputs include the OPCODE field P[32:28], the zero detection flag from the CNTR, and the selected test condition code from the condition code select logic.

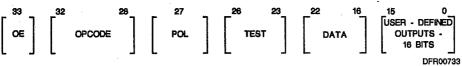
Operational Modes

The Am29PL142 operates as a 7-bit microcontroller in normal mode. By programming the EXP fuse, the output pins P[14:8] can be used as the program address for external registered PROMs. By using external registered PROMs in conjunction with the Am29PL142, control outputs wider than 16 bits can be obtained.

The SSR option provides on-chip diagnostic capabilities for insystem testing. This is accomplished by setting the appropriate conditions on the MODE control input. Note that this can only be done if the SSR diagnostics fuse has been programmed. See Table 1.

The SSR diagnostics configuration activates a 34-bit-wide, D-type register, called a "shadow" register, on the pipeline register inputs. The shadow register can be serially loaded from the SDI pin, parallel loaded from the pipeline register, or held. The pipeline register can be loaded from the program memory in normal operation or from the shadow register during diagnostics. A redefinition of four device pins is required to control the different diagnostics functions. CC also functions as the Serial Data Input (SDI), P[0] becomes the serial data output (SDO), P[7] becomes the diagnostic clock (DCLK), and P[6] becomes the diagnostic mode control (MODE). The various diagnostic and normal modes are shown in Table 1.

Serially loading a test instruction into the shadow register and parallel loading the shadow register contents into the pipeline register forces execution of the test instruction. The test result can then be clocked into the pipeline register, as in normal operation mode, parallel loaded into the shadow register, and serially shifted out for system diagnostics.



WHERE:

ΟE

= Synchronous Output Enable for P[15:8].

OPCODE

- A 5-bit opcode field for selecting one of the 27 single data-field instructions.

POL

A 1-bit test condition polarity select. 0 = Test for true (HIGH) condition. 1 = Test for false (LOW) condition.

TEST

A 4-bit test condition select.

TEST[3:0]	UNDER TEST
0000	T[0]
0001	T[1]
0010	T [2]
0011	T[3]
0100	T[4]
0101	T[5]
0110	T[6]
0111	CC
1000	EQ
1001	CREG ZERO
1010-1111	UNCOND [0]

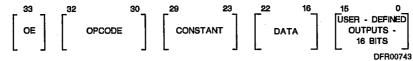
The polarity bit POL in an instruction allows the user to test for a pass/true or fail/false condition as shown in Table 2. An unconditional true is set by selecting UNCOND and POL = 1.

DATA

= A 7-bit conditional branch address, test input mask, or counter value field designated as PL in instruction mnemonics.

The special two data field comparison instruction format is shown below:

Am29PL142 Comparison Instruction Format



WHERE:

OE

= Synchronous Output Enable for P[15:8].

OPCODE = Compare instruction (binary 100).

CONSTANT = A 7-bit constant for equal to comparison with T*M.

= A 7-bit mask field for masking the incoming T[6:0] inputs. DATA

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	Inp	uts			Outputs		
SDI	MODE	DCLK	CLK	SDO	Shadow Register	Pipeline Register	Operation
D	L	t	H,L,‡	So	S _{i-1} ←S _i S ₃₁ ←D	Hold	Serial Right Shift Register
CC**	L	H,L,↓	f	L	Hold	Pi←PROMi	Load Pipeline Register from PROM
L,	н	t	H,L,↓	L	Sį←Pį	Hold	Load Shadow.Register from Pipeline* Register
Х	н	H,L,Į	t	SDI	Hold	Pi←Si	Load Pipeline Register from Shadow Register
Н	Н	1	H,L,↓	Н	Hold	Hold	Hold Shadow Register

^{*} S7, S6 are undefined. If P[33] in the microword is a one, S15-S8 are loaded from the pipeline register. If P[33] in the microword is a zero, S₁₅-S₈ are loaded from an external source.

** During normal operation, this pin behaves as the CC test input.

FUNCTION TABLE DEFINITIONS

INPUTS

D = Serial Data

H = HIGH L = LOW

↑ = LOW-to-HIGH transition

X = Don't Care ↓ = HIGH-to-LOW transition

TABLE 2.

Input Condition Being Tested	POL	Condition
0	0	Fail
0	1	Pass
1	0	Pass
1	1	Fail

Am29PL142 INSTRUCTION SET DEFINITION

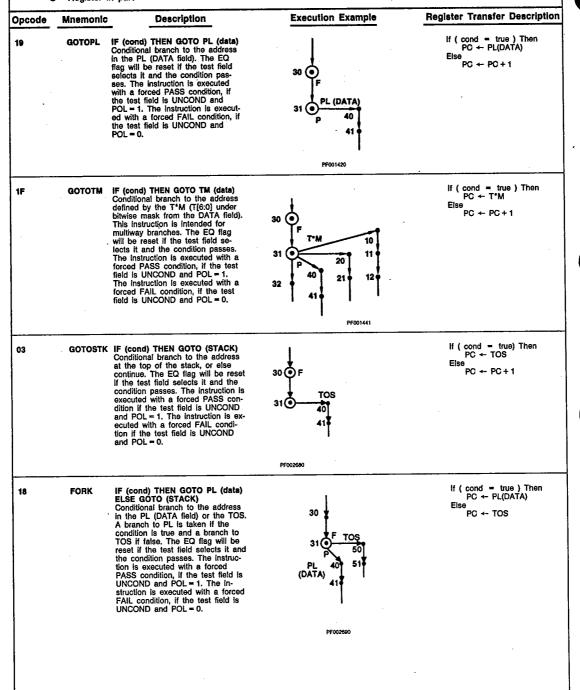
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The stack consists of two registers; the top one is labeled Top of Stack (TOS), the bottom one is labeled Bottom of Stack (BOS).

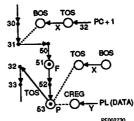
- Other instruction
- ⊙ = Instruction being described
- O = Register in part

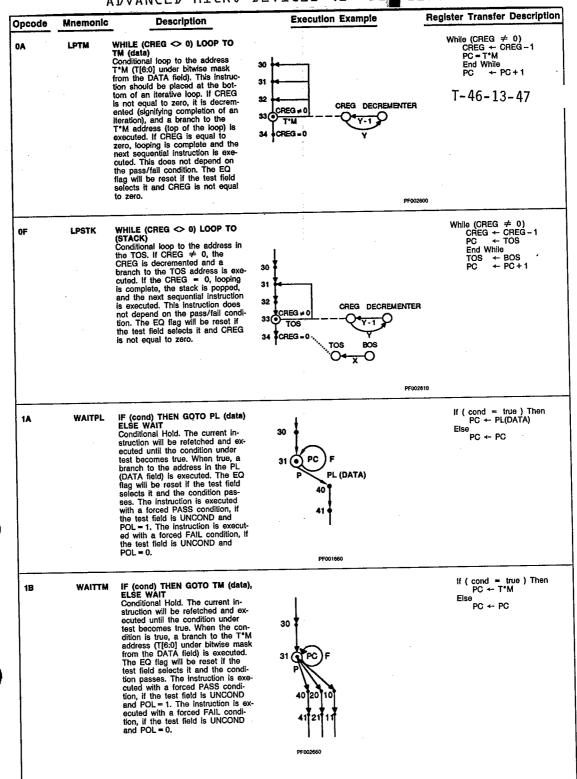
P = Test Pass F = Test Fail

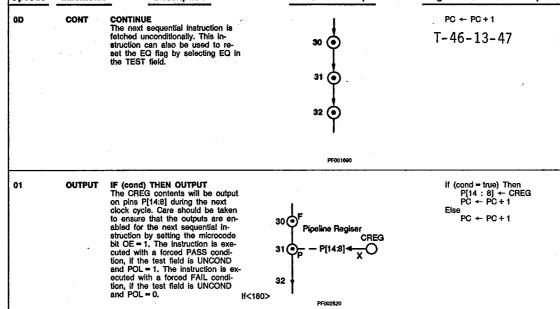
X, Yare arbitrary values in the CREG or STACK



Conditional return from subroutine and load the CREG from the PL (DATA field). The TOS provides the return from subroutine address and the stack is popped. The instruction is executed with a forced PASS condition, if the test field is UNCOND and POL = 1. The instruction is executed with a forced FAIL condition, if the test field is UNCOND and POL = 0.

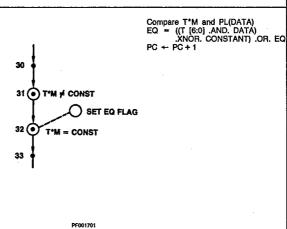






CMP TM (data) TO PL (data)
This instruction performs bitwise exclusive-OR of T*M (T[6:0] under bitwise mask from the DATA field) with CONSTANT (P[29:23]). If T*M equals CONSTANT, the EQ flag is set to one, so that a branch may occur in a following instruction. In ot equal, the EQ flag is unaffected. This allows sequences of compares, in a manner analogous to sum-of-products, to be performed which can be followed by a single conditional branch if one or more of the comparisons were true. 10 – 13 (100XX binary) CMP conditional branch if one or more of the comparisons were true. Note: The EQ flag is set to zero on reset or when EQ is selected as the test condition in a branch. Conditional returns on EQ leave the flag unchanged. Constant fleld bits that correspond to masked test-input bits must be sero. This instruction does not de-

zero. This instruction does not de-pend on the pass/fail condition.



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MICROINSTRUCTIONS BASED ON TEST CONDITIONS

		¥*	•	Condition	Pass		_ :	Conditio	n Fall		
Opcode	Mnemonic	Assembler Statement	PC MUX	STACK	CREG	EQ FLAG	PC MUX	STACK	CREG	EQ FLAG	Notes
00	RETPL	IF (cond) THEN RET, LOAD PL (data)	тоѕ	Рор	Load PL	NC	PC+1	Hold	Hold	NC	5
01	OUTPUT	IF (cond) THEN OUTPUT	PC+1	Hold	Hold	NC	PC+1	Hold	Hold	NC	1
02	RET	IF (cond) THEN RET	TOS	Pop	Hold	NC	PC+1	Hold	Hold	NC	5
03	GOTOSTK	IF (cond) THEN GOTO (STACK)	TOS	Hold	Hold	Reset	PC + 1	Hold	Hold	NC	3
04	LDPL	IF (cond) THEN LOAD PL (data)	PC+1	Hold	Load PL	NC	PC+1	Hold	Hold	NC	
05	PSHCNTR	IF (cond) THEN PUSH (CREG)	PC+1	Push CREG	Hold	NC	PC+1	Hold	Hold	NC	6
06	LDTM	IF (cond) THEN LOAD TM (data)	PC + 1	Hold	Load TM	NC	PC+1	Hold	Hold	NC	
07	POP	IF (cond) THEN POP	PC+1	Рор	Hold	NC	PC+1	Hold	Hold	NC	5
0B	DEC	IF (cond) THEN DEC	PC + 1	Hold	DEC	NC	PC + 1	Hold	Hold	NC	<u> </u>
14	PSHPL	IF (cond) THEN PUSH, LOAD PL (data)	PC+1	Push PC + 1	Load PL	NC	PC+1	Hold	Hold	NC	6
15	PSH	IF (cond) THEN PUSH	PC+1	Push PC + 1	Hold	NC	PC + 1	Hold	Hold	NC	6
16	PSHTM	IF (cond) THEN PUSH, LOAD TM (data)	PC+1	Push PC + 1	Load TM	NC	PC+1	Hold	Hold	NC	6
17	POPCNTR	IF (cond) THEN POP TO (CREG)	PC+1	Рор	Load TOS	NC	PC + 1	Hold	Hold	NC	5
18	FORK	IF (cond) THEN GOTO PL (data) ELSE GOTO (STACK)	PL	Hold	Hold	Reset	TOS	Hold	Hold	NC	3
19	GOTOPL	IF (cond) THEN GOTO PL (data)	PL	Hold	Hold	Reset	PC + 1	Hold	Hold	NC	3
1A	WAITPL	IF (cond) THEN GOTO PL (data) ELSE WAIT	PL	Hold	Hold	Reset	PC	Hold	Hold	NC	3
18	WAITTM	IF (cond) THEN GOTO TM (data) ELSE WAIT	TM	Hold	Hold	Reset	PC	Hold	Hold	NC	3
1C	CALPL	IF (cond) THEN CALL PL (data)	PL	Push PC + 1	Hold	Reset	PC + 1	Hold	Hold	NC	3, 6
1E	CALTM	IF (cond) THEN CALL TM (data)	ТМ	Push PC + 1	Hold	Reset	PC + 1	Hold	Hold	NC	3, 6
1F	GOTOTM	IF (cond) THEN GOTO TM (data)	TM	Hold	Hold	Reset	PC + 1	Hold	Hold	NC	3

Key: TOS = Top of Stack

PC = Program Counter

CREG = Counter Register
PL = Pipeline (DATA) Field

TM = Test Inputs Marked by PL (DATA) Field

DEC = Decrement BOS = Bottom of Stack

NC = No Change

Notes: See notes on next page.

MICROINSTRUCTION DEPENDENT ON CREG

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				CREQ:	= 0			CREG	≠ 0		
Opcode	Mnemonic	Assembler Statement	PC MUX	STACK	CREG	EQ FLAG	PC MUX	STACK	CREG	EQ FLAG	Notes
08	LPPL	WHILE (CREG<>0) LOOP TO PL (data)	PC + 1	Hold	Hold	NC	PL	Hold	DEC	Reset	4
0A	LPTM	WHILE (CREG<>0) LOOP TO TM (data)	PC + 1	Hold	Hold	NC	ТМ	Hold	DEC	Reset	4
0C	DECPL	WHILE (CREG<>0) WAIT ELSE LOAD PL (data)	PC + 1	Hold	Load PL	NC	PC	Hold	DEC	NC	
0E	DECTM	WHILE (CREG<>0) WAIT ELSE LOAD TM (data)	PC + 1	Hold	Load TM	NC	PC	Hold	DEC	ŇC	
OF	LPSTK	WHILE (CREG<>0) LOOP TO (STACK)	PC+1	Hold	Рор	NC	TOS	Hold	DEC	Reset	4

MICROINSTRUCTION DEPENDENT ON TEST CONDITION AND CREG VALUE

					Condition	Pass			Conditio	n Fall		
Opcode	Mnemonic	Assembler Statement	CREG Content	PC MUX	STACK	CREG	EQ FLAG	PC MUX	STACK	CREG	EQ FLAG	Notes
1D	DECGOPL	IF (cond) THEN GOTO PL (data)	≠0	PL	Hold	Hold	Reset	PC	Hold	DEC	NC	3
,,,	DECGOPE	ELSE WHILE (CREG<>0) WAIT	= 0	PL	Hold	Hold	Reset	PC + 1	Hold	Hold	NC	3

UNCONDITIONAL MICROINSTRUCTIONS

Opcode	Mnemonic	Assembler Statement	PC MUX	STACK	CREG	EQ FLAG	Notes
0D	CONT	CONTINUE	PC+1	Hold	Hold	NC	2
10-13 (100XX) Binary	СМР	CMP TM (data) TO PL (data)	PC+1	Hold	Hold	Set	7

Key: TOS = Top of Stack

BOS = Bottom of Stack

PC = Program Counter CREG= Counter Register

PL = Pipeline (DATA) Field

TM = Test Inputs Marked by PL (DATA) Field

DEC = Decrement

NC = No Change

Notes: 1. If Condition Passes, Output CREG contents on next clock cycle.

2. If Condition = EQ, reset EQ flag.

3. If Condition = EQ and Condition Passes, reset EQ flag.

4. If Condition = EQ and CREG ≠ 0, reset EQ flag.

5. When Stack is popped, BOS is transferred to TOS.

6. When Stack is pushed, TOS is transferred to BOS before value is written into TOS.7. Set EQ Flag if CONST field = T*M.

Using The Am29PL142 To Address External Registered PROM

When the EXP fuse is programmed, the program memory MUX is output over pins P[14:8]/A[6:0]. This feature can be used to extend the width of the output control word when external registered PROMs are used. In Figure 5 below, the Am29PL142 addresses external registered PROMs to provide

an output control word (9 + N) bits wide (where N is the bit width of the PROMs). T-46-13-47

When the OUTPUT instruction is executed, the CREG contents are output over pins P[14:8]/A[6:0] on the following cycle. Consequently, if the CREG contents must be read after programming the EXP fuse, the system design should be modified to handle this exception.

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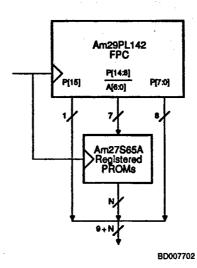


Figure 5. Using Am29PL142 to Address External Registered PROMs

PROGRAMMING

The Am29PL142 FPC is programmed and verified using a simple algorithm that is almost identical to that used for AMD's Programmable Array Logic family. The internal programmable array of the Am29PL142 is organized as a 128-word by 34-bit PROM. The fuse to be programmed is selected by its address (1 of 128), the byte at that address (1 of 5), and the bit in the byte (1 of 8). Control of programming and verifying is accomplished by applying a simple sequence of voltages on two control pins (CLK and CC).

The fuse address is selected using a full decode of the T[6:0] inputs, where T[6] is the MSB and T[0] the LSB. The 1-of-5 byte addressing is done on the P[7] (MSB), and P[6] and P[5] (LSB) outputs. The bit selection is done one output at a time by applying the programming voltage (Vop) to the respective output pin P[15:8]. A graphic representation of the fuse array organization for programming, with fuse numbering compatible to the JEDEC standard programmable logic transfer format, is shown in Figure 6.

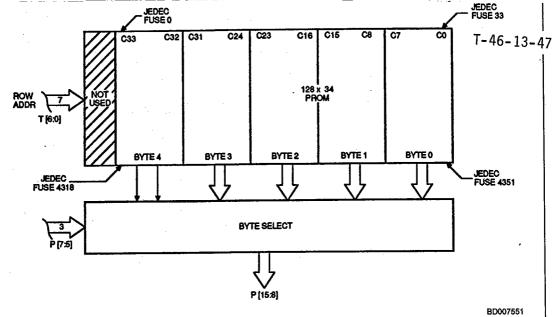
The complete program and verify cycle timing is shown in the programming waveform. A programming sequence is initiated by raising the CLK pin to V_{HH}. This places the device in the program mode and disables the output pins so that they may be used as fuse addressing inputs. The next step is to address the fuse to be blown as previously stated. Note that bit

selection, with Vop, should follow address and byte selection. Raising the CC pin to V $_{\rm HH}$ initiates programming and lowering Vop terminates programming. Lowering the CLK pin to a TTL LOW level places the device in the fuse verification mode by enabling the programming outputs, P[15:8]. Following a clock pulse the fuse may be verified on the same output as bit selection was performed. Using this scheme, fuses can be verified in parallel as a byte if desired. The verification mode is terminated by lowering the CC pin back to a normal TTL level.

Programming Yield

AMD programmable logic devices have been designed to ensure extremely high programming yields (> 98%). To help ensure that a part was correctly programmed (once the programming sequence is completed) the entire fuse array should be reverified at both low and high VCC (VCCL and VCCH). Reverification can be accomplished in a verification-only mode (CC at VHH) by reading the outputs in parallel. This verification cycle checks that the array fuses have been blown correctly and can be sensed under varying conditions by the

AMD programmable logic devices contain extra fuses and circuitry so that it can be verified, before shipping, that all PROM fuses can be programmed. Additional circuitry is included for pre-shipment testing of the logic portion of the device. These added features assure high programming yields and correct logic operation.



JEDEC Fuse Numbering: If Byte \leq 3, Fuse No. = 34 x (Row_Addr) + 8 x (3-Byte) + (7-Bit) + 2 if Byte = 4, Fuse No. = 34 x (Row_Addr) + (1-Bit)

Note: SSR fuse is JEDEC Fuse Number 4352, EXP fuse is JEDEC Fuse Number 4353

Example Computations:

Row 0, Byte 4, Bit 1 Row 127, Byte 0, Bit 0 Fuse No. = 34 (0) + (1-1) = 0

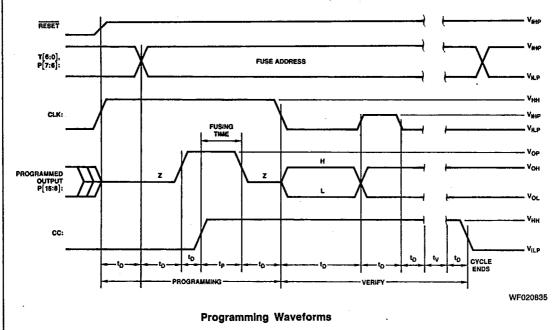
Fuse No. = 34 (127) +8 (3-0) + (7-0) +2 = 4351

-	Byte Select			Bit Select							
Byte	P[7]	P[6]	P[5]	P[15]	P[14]	P[13]	P[12]	P[11]	P[10]	P[9]	P[8]
0	1	1	0	C7	C6	C5	C4	C3	C2	C1	CO
1	1	1	1	C15	C14	C13	C12	C11	C10	C9	C8
2	1	0	0	C23	C22	C21	C20	C19	C18	C17	C16
3	1	0	1	C31	C30	C29	C28	C27	C26	C25	C24
4	0	1	0	-		-	-	-	_	C33	C32
5	0	1	1		-	-	-	-	-	-	
6	0	0	1	-		_	-	-	_	-	
7	0	0	0	SSR	EXP	_	_	_	_	-	-

Notes: 1. Locations with hyphens (-) are reserved. Contents of those locations are unknown and should not be overwritten.
2. T[6:0] gives the row address for programming.
3. C33 is MSB of the Word, C0 is the LSB.
4. Unblown fuses are interpreted as HIGH (1), blown fuses are LOW (0).

Figure 6. Programming Configuration

Parameter Symbol	Parame Descript		Min.	Тур.	Max	Unit	
	a the bull the total	CC @ 5-10 mA	15.5	16	16.5	v	
VHH	Control Pin Extra High Level	CLK@ 5-10 mA	15.5	16	16.5	V	
Vop	Program Voltage, P [15:8] @ 15	5 – 200 mA	19.5	20	20.5	V	
V _{IHP}	Input High Level During Program	nming and Verify	2.4	5	5.5	٧	
VILP	Input Low Level During Program	ming and Verify	0.0	0.3	0.5	٧	
VCCP	V _{CC} During Programming @ I _{CC}	= 500 mA	5	5.2	5,5	٧	
V _{CCL}	V _{CC} During First Pass Verification	1 @ ICC = 500 mA	4.5	4.7	5	٧	
Vccн	V _{CC} During Second Pass Verifica	tion @ ICC = 545 mA	5.4	5.7	6.0	V	
VBlown	Successful Blown Fuse Sense I	evel @ Output		0.3	0.5	٧	
dV _{OP} /dt	Rate of Output Voltage Change		20		250	V/μs	
dV _{FE} /dt	Rate of Fusing Enable Voltage C	hange (CC Rising Edge)	100		1000	V/µs	
tp	Fusing Time First Attempt		40	50	100	μs	
	Subsequent Attempts		4	5	10	ms	
t _D	Delays Between Various Level	Changes	100	200		ns	
ty	Period During which Output is Se	nsed for V _{Blown} Level	500			ns	
VONP	Pull-Up Voltage on Outputs Not	Being Programmed	V _{CCP} - 0.3	V _{CCP}	V _{CCP} + 0.3	٧	
R	Pull- Up Resistor on Outputs N	ot Being Programmed	1.9	2	2.1	kΩ	
dV _{CLK/dt}	Rate of CLK Voltage Change (I	Programming)	40	50	250	V/µs	
	Rate of CLK Voltage Change (/erify)	250	300	1000	V/μs	



ABSOLUTE MAXIMUM RATINGS

Storage Temperature-65 to +150°C (Ambient) Temperature Under Bias-55 to +125°C Supply Voltage to Ground Potential (Pin 28 to Pin 14) Continuous-0.5 V to +7.0 V DC Voltage Applied to Outputs (Except During Programming)......-0.5 V to +V_{CC} Max. DC Voltage Applied to Outputs Programming (Max Duration of 1 s) 200 mA DC Input Voltage-0.5 V to +5.5 V DC Input Current-30 mA to +5.0 mA Stresses above those listed under ABSOLUTE MAXIMUM

RATINGS may cause permanent device failure. Functionality

at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device

reliability.

OPERATING RANGES

DE

Commercial (C) Devices Ambient Temperature (T _A)
Military* (M) Devices Case Temperature (T _C)55 to +125°C Supply Voltage (V _{CC})+4.5 V to +5.5 V
Operating ranges define those limits between which the functionality of the device is guaranteed.
*Military Product 100% tested at T _C = +25°C, +125°C and -55°C.
Typical θ μ

Typical θ_{JC}......3°C/W

DC CHARACTERISTICS over operating range unless otherwise specified (for APL Products, Group A. Subgroups 1, 2, 3 are tested unless otherwise noted)

Parameter Symbol	Parameter Description	Test Conditions				Min.	Max.	Unit		
	O-1 111011 V-1	V _{CC} = Min., COM'L 29PL142 I _{OH} = ~3.0 mA				2.4		v		
Vон	Output HIGH Voltage	VIN = VIH or V	IL MI	L	29PL14	12	I _{OH} = -1.0 mA	2.4		
14-	0.1-1.1.0141.1/-11	V _{CC} = Min.,	CC)M'L	29PL14	12	IOL = 16 mA		0.50	V
VOL	Output LOW Voltage	VIN = VIL or V	H MI	<u>L</u>	29PL14	12	I _{OL} = 12 mA			
V _{IH} (Note 1)	Input HIGH Level	Guaranteed Input Logical HIGH Voltage for All Inputs				2.0		٧		
V _{IL} (Note 1)	Input LOW Level	Guaranteed Input Logical LOW Voltage for All Inputs				0.8	٧			
t _{IL}	Input LOW Current	V _{CC} = Max. CLK P [15:6] V _{IN} = 0.5 V All Char Inputs			-1.5 -0.55	mA				
115	mps: 2007 Garrett	V _{IN} = 0.5 V	All Other Inputs					-0.50		
	I 111011 O1	VCC = Max. CLK				150 100		μА		
ĮН	Input High Current	ut HIGH Current VIN = 2.4 V P [15:6] All Other Inputs				25	"			
-li	Input HIGH Current	V _{CC} = Max., V _{IN} = 5.5 V					1.0	mA		
Isc	Output Short-Circuit Current	V _{CC} = Max + 0.5 V V _{OUT} = 0.5 V (Note 2)				-20	-80	mA		
	Barra Strate Cornel	Vcc = Max.	COM'L	29PL142		TA	= 0 to +70°C		500	
						T _A = +70°C			450	mA
lcc	Power Supply Current		MIL	29PL142		T _C = -55 to +125°C		_	570	11115
			MIL	25	23FL142		= + 125°C	475		
V _I	Input Clamp Voltage	V _{CC} = Min, I _{IN}	V _{CC} = Min, I _{IN} = -18 mA				-1.2	٧		
^l ozh	Output Leakage Current	V _{CC} = Max., V	= Max., V _{IL} = 0.8 V V _O = 2.4 V					100	μА	
lozL	(Note 3)	$V_{IH} = 2.0 \text{ V}$ $V_{O} = 0.5 \text{ V}$				-550				

Notes: 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.

2. Not more than one output should be tested at a time. Duration of the short-circuit test should not be more than one second.

Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.

3. I/O pin leakage is the worst-case of lozx or lix (where X = H or L).

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SWITCHING CHARACTERISTICS over operating range unless otherwise specified (for APL Products, Group A, Subgroups 9, 10, 11 are tested unless otherwise noted)

				CO	COM'L		MIL	
No.	Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Min.	Max.	Unit
1		CLK to P[15:0]			20		25	ns
2		CLK to A[6:0]			50		55	ns
3	t _{PD}	DCLK to SDO			30	<u></u>	30	ns
4		Mode to SDO			30		30	ns
5		SDI to SDO			30		30	ns
6		T[6:0] to CLK (Note 1)		15		15		ns
7		CC to CLK (Note 1)		15		15		ns
B -		RESET to CLK		15		15		ns
9	ts	Mode to CLK		30		30		ns
10		Mode to DCLK		30		30	L	ns
11		SDI to DCLK		30		30		ns
12		P[15:8] to DCLK		30		30	<u> </u>	ns
13		T[6:0] to CLK	See Test	0	<u> </u>	0	<u> </u>	ns
14		CC to CLK	Output Load Conditions	0		0		ns
15	- - - -	RESET to CLK		4		0		ns
16		Mode to CLK		0		0_		ns
17		Mode to DCLK		0	<u> </u>	0		ns
18		SDI to DCLK		0		0	<u> </u>	ns
19		P[15:8] to DCLK		0		0		ns
20	tezx	CLK to P[15:8] Enable			20		25	ns
21	texz	CLK to P[15:8] Disable		Ĺ	30		30	ns
22	tpwH	CLK Pulse Width (HIGH)		15		15	<u> </u>	пя
23	tpwL	CLK Pulse Width (LOW)		25		30		ns
24	tpw	DCLK Pulse Width (HIGH and LOW)	1	30		30	L	ns
25	tp	CLK Period (Notes 1 & 2)	1	50		65		ns

Notes: 1. These parameters are measured indirectly on unprogrammed devices. They are determined as follows:

a. Measure delay from input (T[6:0], or CLK) to PROM address out in test mode. This will measure the delay through the sequence

a. Measure delay from input (1[0:0], or CLP) to FIROM addices out in Section 1.
b. Measure setup time from T[6:0] input through PROM test columns to pipeline register in verify test column mode. This will measure the delay through the PROM and register setup.
c. Measure delay from T[6:0] input to PROM address out in verify test column mode. This will measure the delay through the logic and P[15:0] outputs.
To calculate the desired parameter measurement the following formula is used:

Measurement (a) + Measurement (b) - Measurement (c)

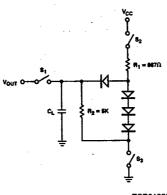
CLK PERIOD:

CLK (al + (b) - (c) = CLK PERIOD

CLK (a) + (b) - (c) = CLK PERIOD

2. CLK rise time must not exceed 7 ns.

SWITCHING TEST CIRCUITS



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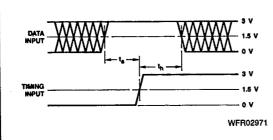
TCR01330

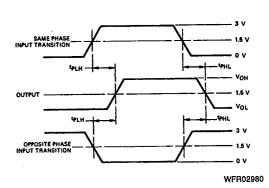
A, Three State Outputs

B. Normal Outputs

- Notes: 1. CL = 50 pF includes scope probe, wiring and stray capacitances without device in test
 - 2. $S_1,\ S_2,\ \text{and}\ S_3$ are closed during function tests and all AC tests except output enable tests.
 - 3. S_1 and S_3 are closed while S_2 is open for tp_{ZH} test. 4. C_L = 5.0 pF for output disable tests.

SWITCHING TEST WAVEFORMS





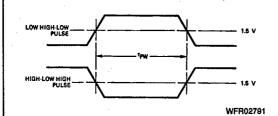
Setup, Hold, and Release Times

- Notes: 1. Diagram shown for HIGH data only. Output transition may be opposite sense.
 - 2. Cross hatched area is don't care condition,

Propagation Delay

SWITCHING TEST WAVEFORMS (Cont'd.)

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Test	V _X	Output Waveform — Messurement Level
All toDs	5.0V	VOH 1.5V
t _{PHZ}	V0.0	V _{OH} 0.5V
t _{PLZ}	5.0V	VOL
[‡] РZН	0.0V	0.0V VOH
tezL	5.0V	1.5V V _{OL}

WFR02680

Pulse Width

Enable and Disable Times

- Notes: 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
 2. S₁, S₂, and S₃ of Load Circuit are closed except where shown.

Note: Pulse generator for all pulses: Rate \leq 1.0 MHz; Z0 = 50 Ω : t/ \leq 2.5 ns.

Test Philosophy and Methods

The following points give the general philosophy that we apply to tests that must be properly engineered if they are to be implemented in an automatic environment. The specifics of what philosophies applied to which test are shown.

- Ensure the part is adequately decoupled at the test head. Large changes in supply current when the device switches may cause function failures due to VCC changes.
- Do not leave inputs floating during any tests, as they may oscillate at high frequency.
- 3. Do not attempt to perform threshold tests at high speed. Following an input transition, ground current may change by as much as 600 mA in 5-8 ns. Inductance in the ground cable may allow the ground pin at the device to rise by hundreds of millivolts momentarily. Current level may vary from product to product.
- 4. Use extreme care in defining input levels for AC tests. Many inputs may be changed at once, so there will be significant noise at the device pins that may not actually reach V_{IL} or V_{IH} until the noise has settled. AMD recommends using $V_{IL} \leqslant 0$ V and $V_{IH} \geqslant 3.0$ V for AC tests.
- To simplify failure analysis, programs should be designed to perform DC, Function, and AC tests as three distinct groups of tests.
- 6. Capacitive Loading for AC Testing

Automatic testers and their associated hardware have stray capacitance that varies from one type of tester to another but is generally around 50 pF. This, of course, makes it impossible to make direct measurements of parameters that call for smaller capacitive load than the associated stray capacitance. Typical examples of this are the so-called "float delays," which measure the propagation delays into the high impedance state and are usually specified at a load capacitance of 5.0 pF. In these cases, the test is performed at the higher load capacitance (typically 50 pF) and engineering correlations based on data taken with a bench set up are used to predict the result at the lower capacitance.

Similarly, a product may be specified at more than one capacitive load. Since the typical automatic tester is not capable of switching loads in mid-test, it is impossible to make measurements at both capacitances even though they may both be greater than the stray capacitance. In

these cases, a measurement is made at one of the two capacitances. The result at the other capacitance is predicted from engineering correlations based on data taken with a bench set up and the knowledge that certain DC measurements (IOH, IOL, for example) have already been taken and are within spec. In some cases, special DC tests are performed in order to facilitate this correlation.

7. Threshold Testing

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The noise associated with automatic testing (due to the long inductive cables), and the high gain of the tested device when in the vicinity of the actual device threshold, frequently give rise to oscillations when testing high-speed speed circuits. These oscillations are not indicative of a reject device, but instead, of an overtaxed test system. To minimize this problem, thresholds are tested at least once for gach input pin. Thereafter, "hard" high and low levels are used for other tests. Generally this means that function and AC testing are performed at "hard" input levels rather than at VIL Max. and VIH Min.

8. AC Testing

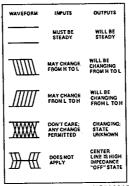
Occasionally, parameters are specified that cannot be measured directly on automatic testers because of tester limitations. Data input hold times often fall into this category. In these cases, the parameter in question is guaranteed by correlating these tests with other AC tests that have been performed. These correlations are arrived at by the cognizant engineer by using data from precise bench measurements in conjunction with the knowledge that certain DC parameters have already been measured and are within spec.

In some cases, certain AC tests are redundant since they can be shown to be predicted by other tests that have already been performed. In these cases, the redundant tests are not performed.

9. Output Short-Circuit Current Testing

When performing I_{OS} tests on devices containing RAM or registers, great care must be taken that undershoot caused by grounding the high-state output does not trigger parasitic elements which in turn cause the device to change state. To avoid this effect, it is common to make the measurement at a voltage (V_{output}) that is slightly above ground. The V_{CC} is raised by the same amount so that the result (as confirmed by Ohm's law and precise bench testing) is identical to the V_{OUT} = 0, V_{CC} = Max. case.

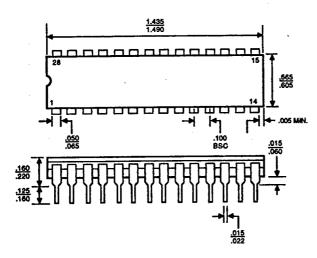
SWITCHING WAVEFORMS KEY TO SWITCHING WAVEFORMS

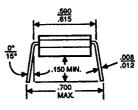


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PHYSICAL DIMENSIONS* CD 028





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